To: Molex Customers

From: Molex Product Marketing

Date: August 16, 2011

Subject: Transitioning Beryllium Copper HDM connectors to Beryllium Free

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In support of our global environmental initiatives, Molex is in the early stages of planning the elimination of Beryllium in the HDM Backplane Power Module Connector family. We expect to transition connectors currently supplied with Beryllium Copper to a Beryllium-free High Performance Copper Alloy no later than December 1st, 2011.

The product series affected are 73656, 73659 and 75894.

This is a running change and we will keep the same part number(s) unless a specific request is made to change the part number(s) that you purchase.

Going forward Molex will no longer offer Beryllium-Copper base material for any new part numbers in the HDM family.

Thank you in advance for your understanding and please feel free to contact Molex with questions and / or concerns.